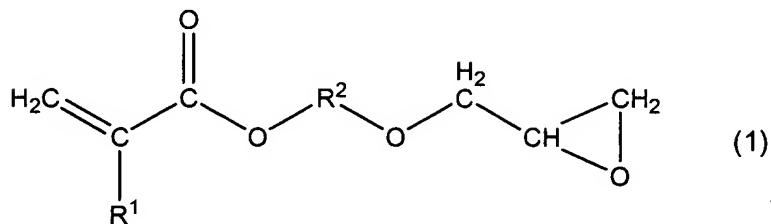


ABSTRACT OF THE DISCLOSURE

The photosensitive resin composition is composed of a poly((meth)acrylic acid)-based water-soluble photo-sensitive resin (A) having an acid value of 150 mgKOH/g or more on a solid basis; the resin (A) being formed of a ((meth)acrylic acid)-based polymer in which a compound represented by formula (1):



(wherein R<sup>1</sup> represents H or Me; and R<sup>2</sup> represents a liner or branched C2-C10 alkylene group) has been added to portions of the carboxylic groups, a photopolymerization initiator (B); and water (C).